ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entries the declaration entries and t	on of the su	bstances v all lower	within the manufactur level materials for w	rer listed it hich the m	em. Note: anufacture	if the item is an as er has engineering	sembly with low responsibility.
52.21.1 IPC Web Site for Information on IPC-1752 Standard Fo			Form Type Distribute					ials and Mfg Information					
Supplier Information													
Company name* Company un			nique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-20			
Contact Name	tact Name Title - Contact					Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Enviro			ro Compliance		NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represe			sentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	ve Date Version Manufacturing Site		7	Weight*	UOM	Unit Type	
	SZMMS	ZMMSZ5235ET1G ZENER REGULA		ATOR DIODE	R DIODE 2024-04		CN1		N1	11.67		mg	Each
Ianufacturing Proccess Informa	tion									·			
Terminal Plating / Grid Array Ma	aterial 7	ial Terminal Base Alloy		J-STD-020 MSI	L Rating	Peak Process Bo		Body Temperature Max Time at Peak		Temperat	ure Num	ber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secon	ds 3		
omments													
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.88	mg	Supplier	Silicon (Si)	7440-21-3		0.88	mg	
Lead Frame	3.19	mg	В	Nickel (Ni)	7440-02-0		1.158	mg	
			Supplier	Iron (Fe)	7439-89-6		1.6014	mg	
			Supplier	Copper (Cu)	7440-50-8		0.4306	mg	
Mold Compound-Black	6.51	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.651	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0325	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.9439	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		4.2315	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.651	mg	
Plating	0.8	mg	Supplier	Tin (Sn)	7440-31-5		0.8	mg	
Wire Bond	0.29	mg	Supplier	Palladium (Pd)	7440-05-3		0.0038	mg	
			Supplier	Copper (Cu)	7440-50-8		0.2862	mg	